HAT2057RA

Silicon N Channel Power MOS FET High Speed Power Switching

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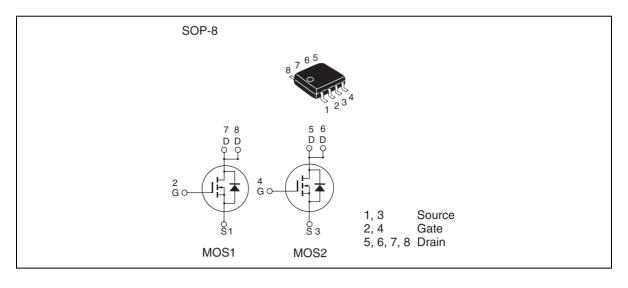
ADE-208-1636 (Z)

1st. Edition Feb. 2003

Features

- Low on-resistance
- Capable of 1.5 V gate drive
- Low drive current
- High density mounting

Outline





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Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit	
Drain to source voltage	V_{DSS}	20	V	
Gate to source voltage	V _{GSS}	+6,-3	V	
Drain current	I _D	4	Α	
Drain peak current	I _{D(pulse)} Note1	32	Α	
Body-drain diode reverse drain current	I _{DR}	4	Α	
Channel dissipation	Pch Note2	2	W	
Channel dissipation	Pch Note3	3	W	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1 %

- 2. 1 Drive operation: When using the glass epoxy board (FR4 40 x 40 x 1.6 mm), PW≤ 10s
- 3. 2 Drive operation: When using the glass epoxy board (FR4 40 x 40 x 1.6 mm), PW≤ 10s

Electrical Characteristics

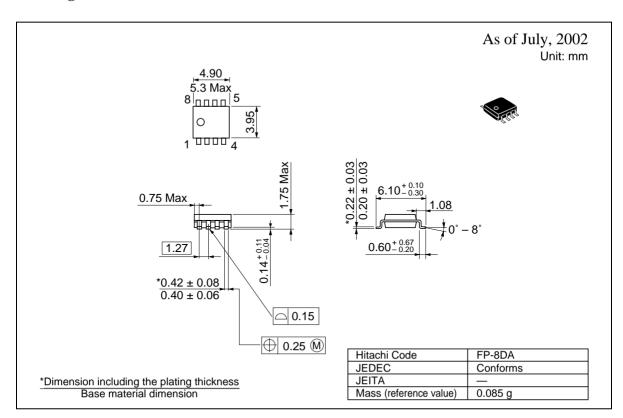
 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	20	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source leak current	I _{GSS}	_	_	±0.2	μΑ	$V_{GS} = +6 \text{ V}, -3\text{V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	10	μΑ	$V_{DS} = 10 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	V _{GS(off)}	0.15	_	0.90	V	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{mA}$
Static drain to source on state	R _{DS(on)}	_	26	33	mΩ	$I_D = 2 \text{ A,V}_{GS} = 4 \text{ V}^{\text{Note4}}$
resistance	R _{DS(on)}	_	40	60	mΩ	$I_D = 2 \text{ A,V}_{GS} = 1.5 \text{ V}^{\text{Note4}}$
Forward transfer admittance	y _{fs}	8	13	_	S	$I_D = 2 \text{ A,V}_{DS} = 10 \text{ V}^{\text{Note4}}$
Input capacitance	Ciss	_	1100	_	pF	V _{DS} = 10 V
Output capacitance	Coss	_	155	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	125	_	pF	f = 1 MHz
Turn-on delay time	t _{d(on)}	_	15	_	ns	$V_{GS} = 4 \text{ V}, I_D = 2 \text{ A}$
Rise time	t _r	_	25	_	ns	$V_{DD} \cong 10 \text{ V}$
Turn-off delay time	t _{d(off)}	_	65	_	ns	$R_g = 4.7 \Omega$
Fall time	t _f	_	13	_	ns	$R_L = 5 \Omega$
Body-drain diode forward voltage	V_{DF}	_	0.80	1.04	V	$IF = 4$, $V_{GS} = 0$ Note4
Body-drain diode reverse recovery time	t _{rr}	_	40	_	ns	$IF = 4A$, $V_{GS} = 0$ diF/ dt =20 A/ μ s

Notes: 4. Pulse test

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Package Dimensions



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